

30V P-Channel Enhancement Mode MOSFET**Description**

The PECN3401 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

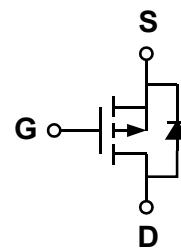
- ◆ $V_{DS} = -30V$, $I_D = -4.2A$
 $R_{DS(ON)}(\text{Typ.}) = 53m\Omega$ @ $V_{GS} = -4.5V$
- ◆ $R_{DS(ON)}(\text{Typ.}) = 73m\Omega$ @ $V_{GS} = -2.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

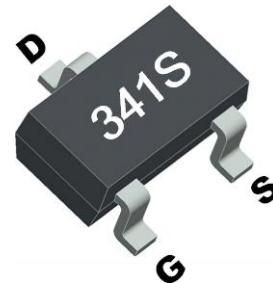
- ◆ PWM applications
- ◆ Load switch

Package

- ◆ SOT-23

**Schematic diagram****Marking and pin assignment**

SOT-23
(TOP VIEW)

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN3401V R-G	-55°C to +150°C	SOT-23	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage	V_{GS}	± 12	V
Continuous Drain Current (TJ = 150 °C)	I_D	-4.2	A
		-3.5	
		-3.7 ^{b,c}	
		-2.9 ^{b,c}	
Continuous Source-Drain Diode Current	I_S	-1.4	A
		-1 ^{b,c}	
Pulsed Drain Current ($t = 300 \mu s$)	I_{DM}	-12.8	

Maximum power dissipation	T _C =25°C	P _D	1.7	W
	T _C =70°C		1.1	
	T _A =25°C		1 ^{b,c}	
	T _A =70°C		0.6 ^{b,c}	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55—150	°C

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{θJA}	100	130	°C/W
Maximum Junction-to-Foot (Drain)	R _{θJF}	60	75	

Notes:

- a. TC = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 175 °C/W.

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.5	-0.83	-1.3	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-4A	-	53	65	mΩ
		V _{GS} =-2.5V, I _D =-1A	-	73	85	
Forward transconductance	g _{fs}	V _{DS} =-5V, I _D =-4A	-	11	-	S
Dynamic Characteristics						
IPECNut capacitance	C _{ISS}	V _{DS} =-15V, V _{GS} =0V f=1.0MHz	-	880	-	pF
Output capacitance	C _{OSS}		-	105	-	
Reverse transfer capacitance	C _{RSS}		-	65	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DD} =-15V I _D =-4A V _{GEN} =-10V R _L =3.6ohm R _{GEN} =60hm	-	7	-	ns
Rise time	t _r		-	3	-	
Turn-off delay time	t _{D(OFF)}		-	30	-	
Fall time	t _f		-	12	-	
Total gate charge	Q _g	V _{DS} =-15V, I _D =-4A V _{GS} =-4.5V	-	8.5	-	nC
Gate-source charge	Q _{gs}		-	1.8	-	
Gate-drain charge	Q _{gd}		-	2.7	-	

DRAIN-SOURCE DIODE CHARACTERISTICS

Diode forward voltage	V_{SD}	$V_{GS}=0V, I_s=-4A$	-	-0.81	-1.2	V
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Typical Performance Characteristics

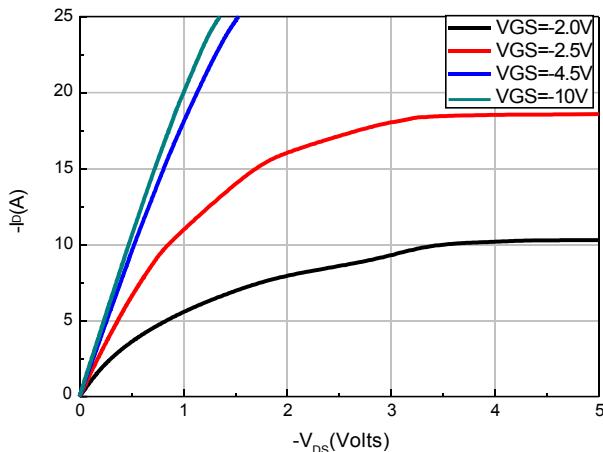


Fig 1: On-Region Characteristics

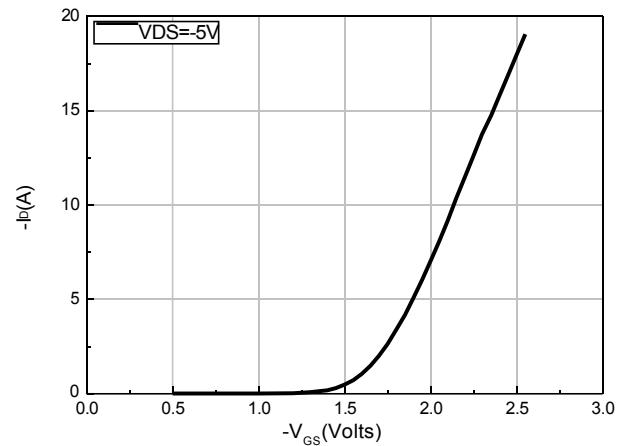


Figure 2: Transfer Characteristics

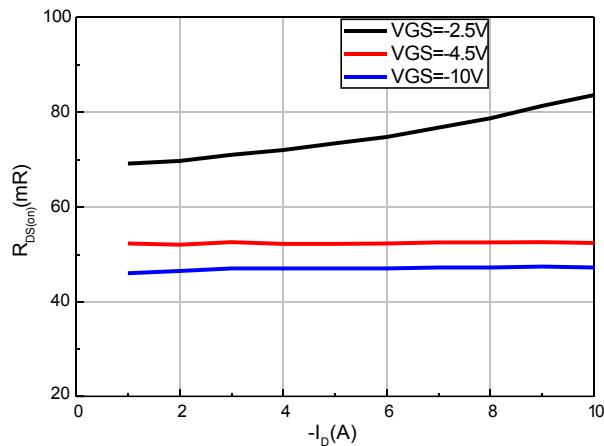


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

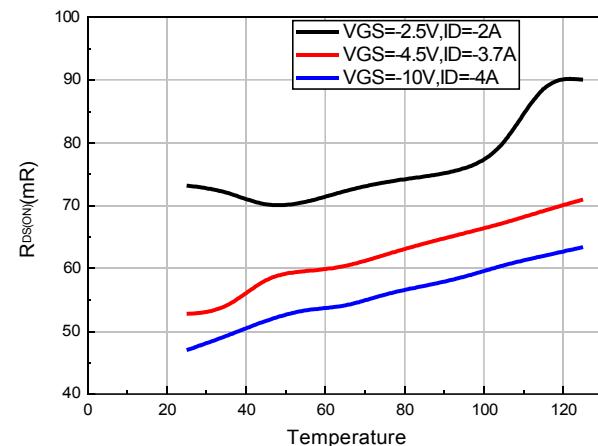


Figure 4: On-Resistance vs. Junction Temperature

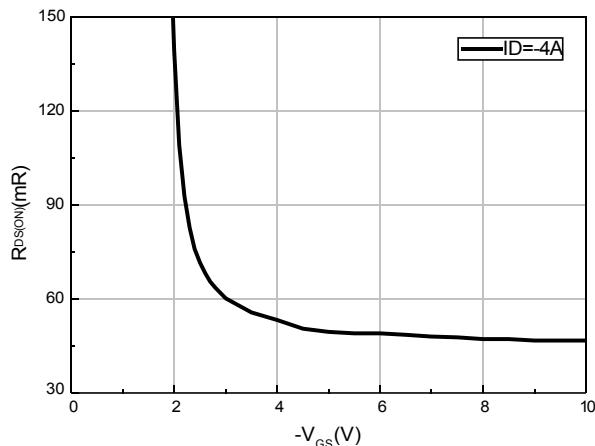


Figure 5: On-Resistance vs. Gate-Source Voltage

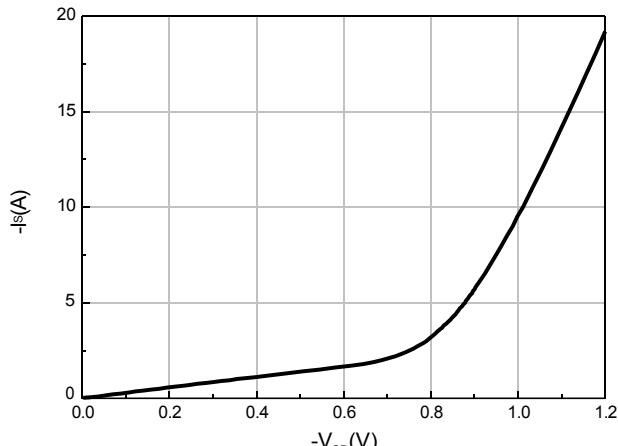
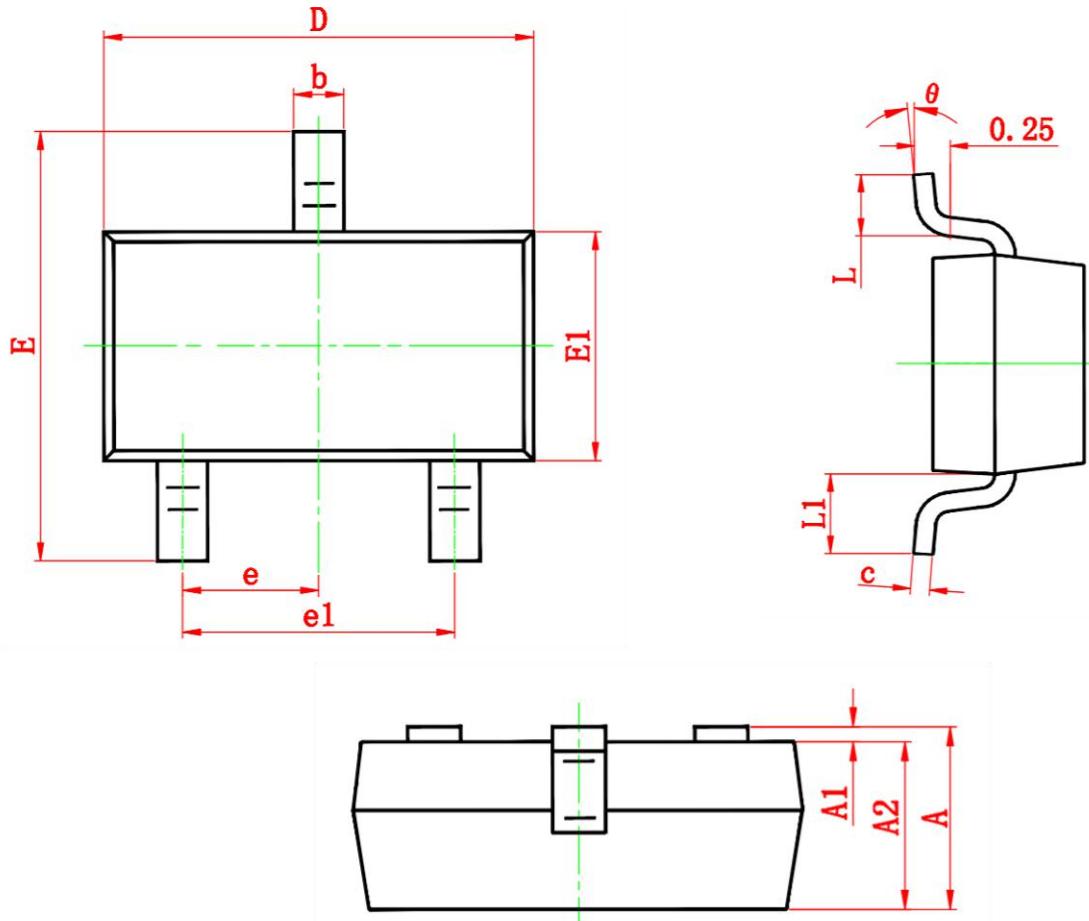


Figure 6: Body-Diode Characteristics

Package Information

- SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
theta	0°	8°	0°	8°